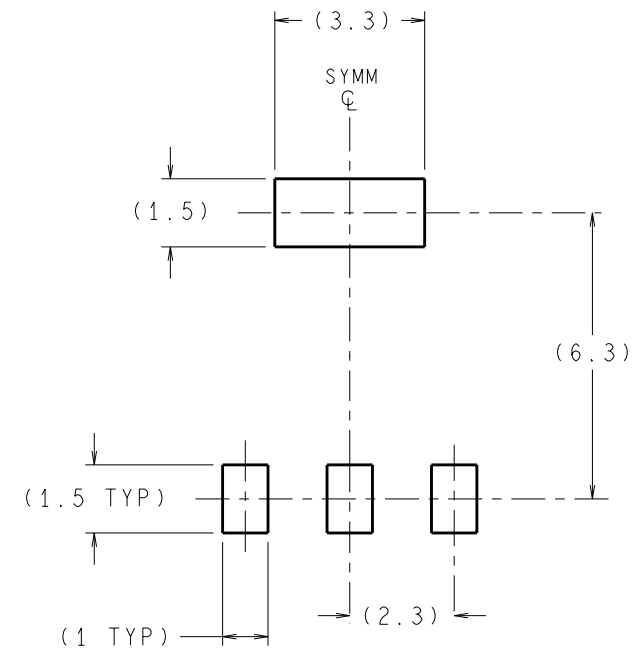
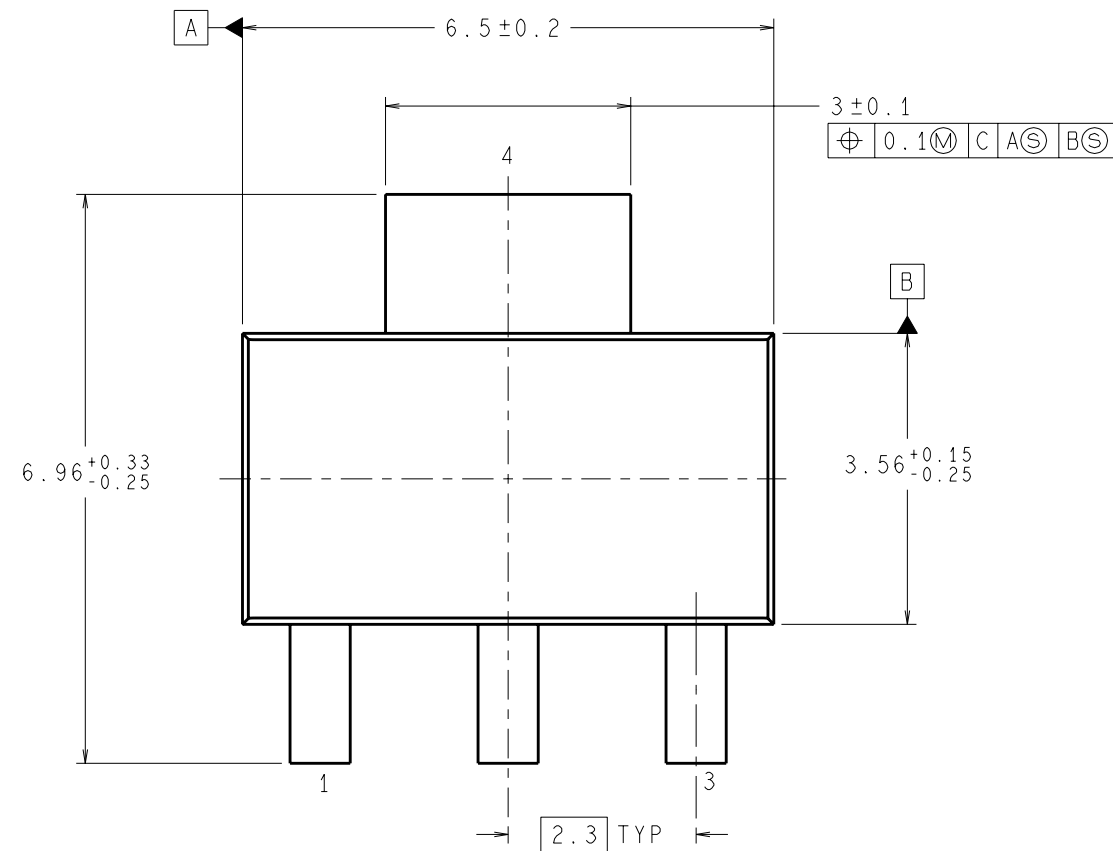
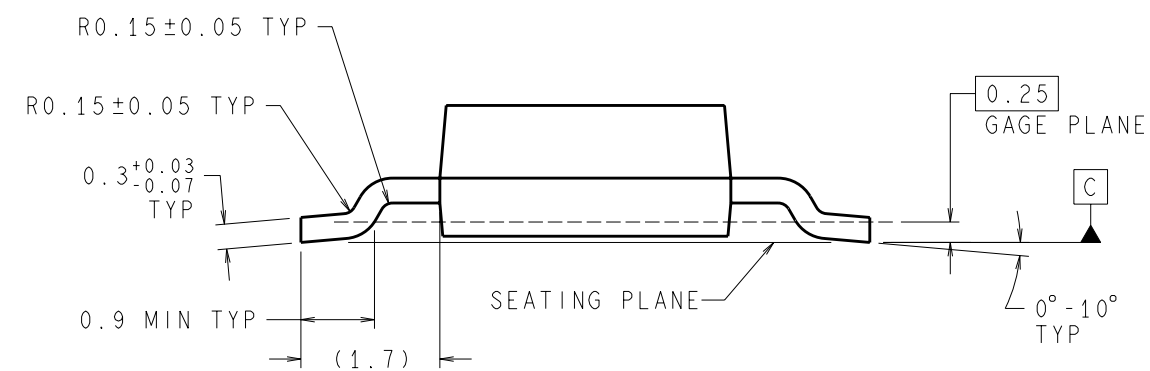
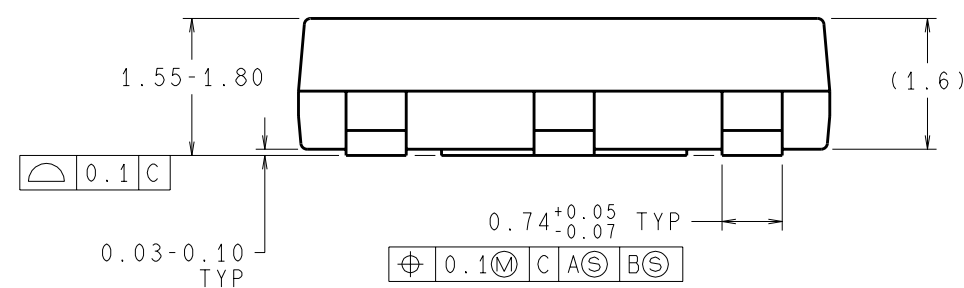


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12365	01/12/2000	MS/RW



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
- REFERENCE JEDEC REGISTRATION TO-261, VARIATION AA, ISSUE B, DATED FEBRUARY 1999.

APPROVALS	DATE	National Semiconductor		
DRAWN MARTA SUCHY	01/12/2000	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG	01/14/2000	MOLDED SOT-223, 6.5 X 3.56 X 1.6mm BODY, 4 LEAD, 2.3mm PITCH		
ENGR. CHK. THANH LEQUANG	01/14/2000	SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-MP04A
		DO NOT SCALE DRAWING	REV A	SHEET 1 of 1